

# Behavioural Modelling for Stability of CMOS SRAM Cells Subject to Random Discrete Doping

**Yangang Wang**

Mark Zwolinski

Michael A Merrett

E-mail: [yw2@ecs.soton.ac.uk](mailto:yw2@ecs.soton.ac.uk)

University of Southampton, UK

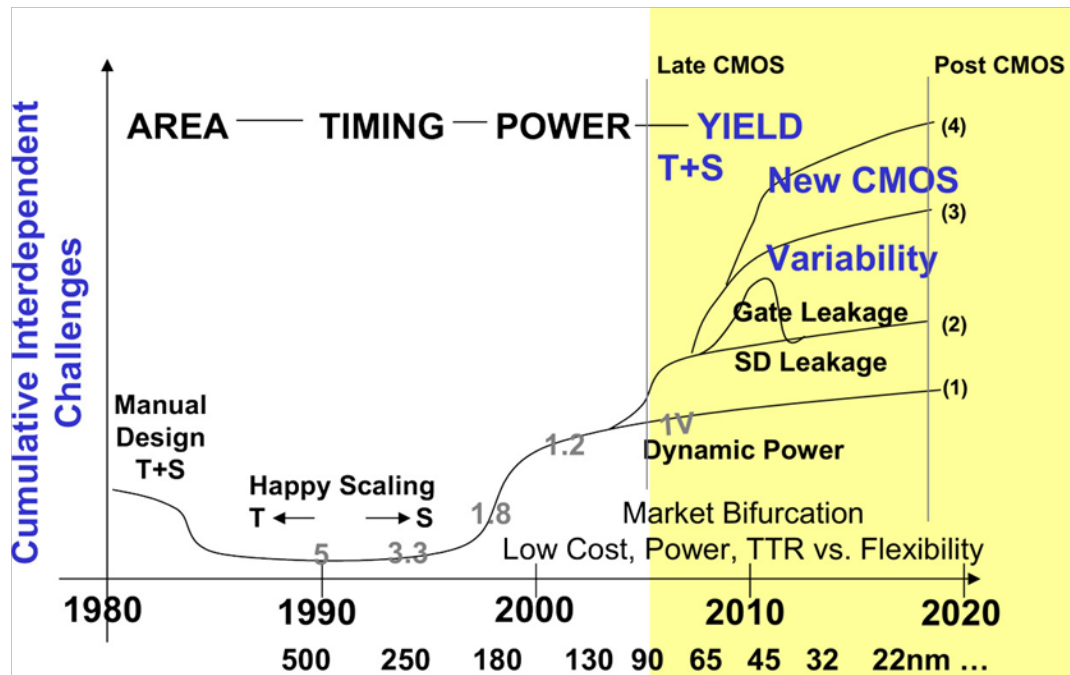
26<sup>th</sup> Sep. 2008

# Outline

- **Background**
- **Effects of  $R_{\text{random}}$   $D_{\text{discrete}}$   $D_{\text{doping}}$  on CMOS SRAM**
- **VHDL-AMS Behavioural Model Development**
- **Verification by SPICE**
- **Conclusions**

## ➤ Background — Variability

**Variability** is becoming a major challenge in the near future



### ➤ Source of variability

#### **Intrinsic,**

Atomic-level differences between devices,  
Irrespective of layout and environment.

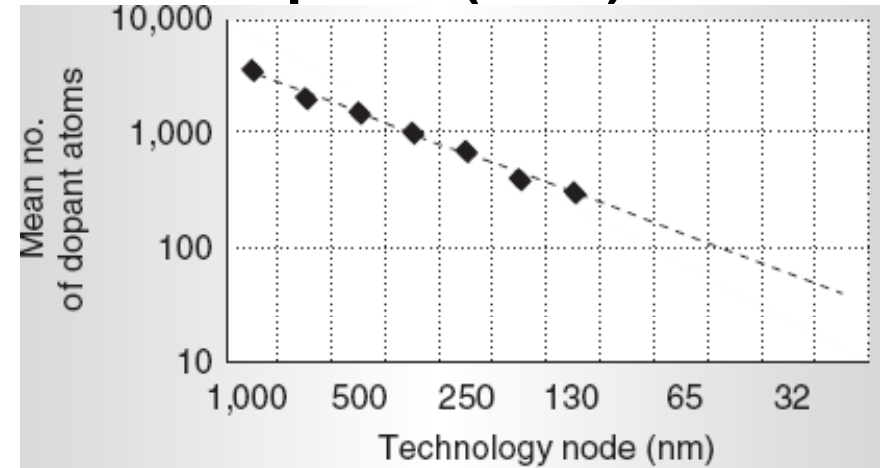
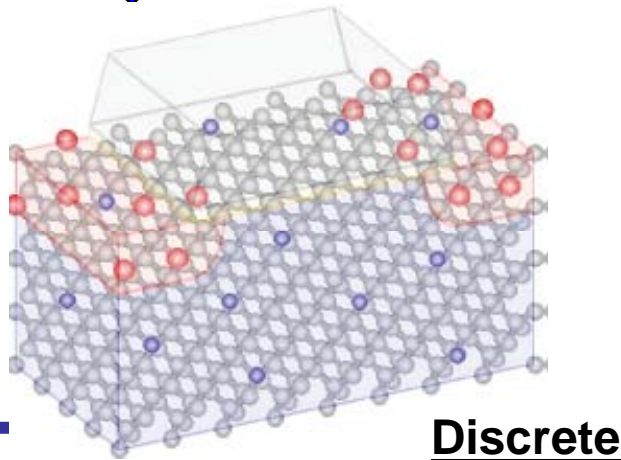
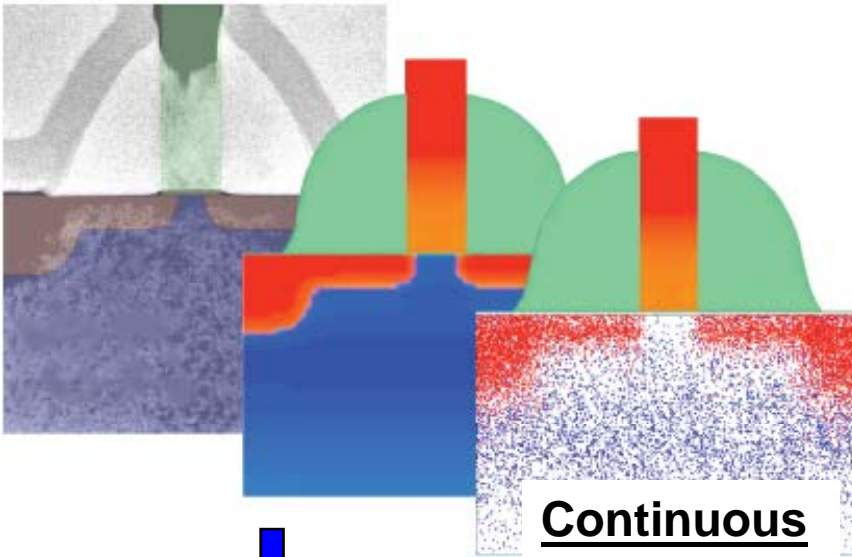
#### **Extrinsic,**

- lot to lot;
- wafer to wafer;
- across wafer;
- chip to chip;
- within a chip.

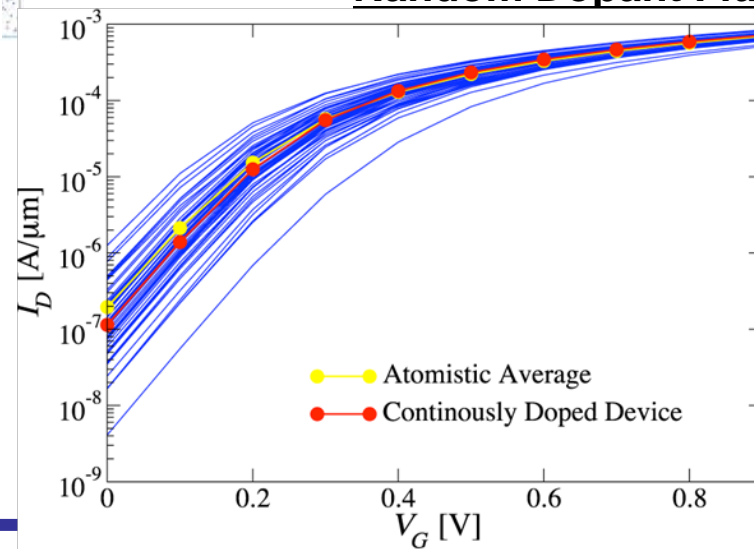
G. Declerck, VLSI Technol. Symp., 2005, p. 6-10

# ➤ Background — Variability (Cont.)

## ✓ Intrinsic Variability — Random Discrete Dopants (RDD)



### Random Dopant Fluctuations



**$I_{ds}$  and  $V_{th}$   
Variations**

## ➤ Background — Variability (Cont.)

- ✓ Intrinsic Variability — Line Edge Roughness (**LER**):  $L_g$ , Interconnect;
- Oxide Thickness Fluctuations (**OTF**): Leakage;
- Poly Silicon Grain Boundaries.

Fluctuation (mV)	$V_{th}$ (Ave)	$\sigma V_{th}$	Calc. $\sigma V_{th}$
<b>RDD</b>	<b>133</b>	<b>33.2</b>	
LER	126	19	
OTF	122	1.8	
RDD&LER	126	38.7	38.2
RDD&OTF	123	33.9	33.3
LER&OTF	113	22.8	19.1

Source	$\sigma V_{th}$ (mV)	Comment
RDD&LER&OTF	40	<b>35nm</b> , Simulation
H. Fukutome	49	40nm
F. Arnaud	63	65nm

**Effects of RDD, LER, OTF on 35 nm conventional MOSFET,**  
From Glasgow Device Modelling Group Reports

## ➤ Background — Modelling Hierarchy

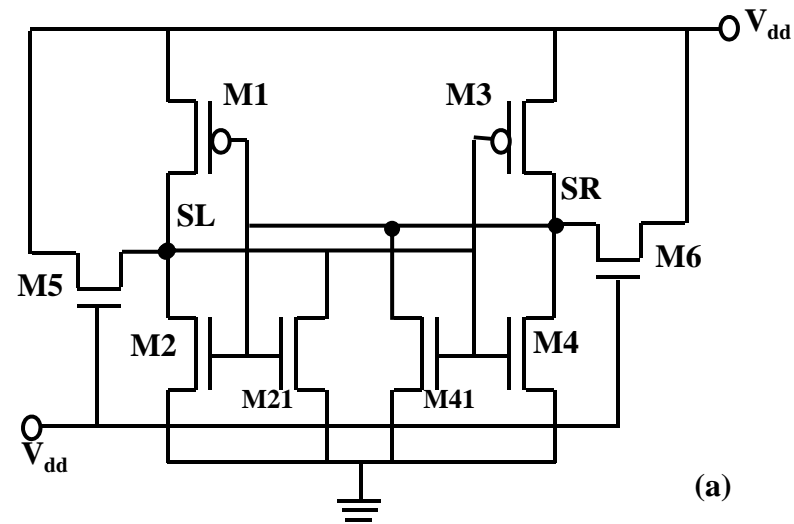
- Transistor-Level (TCAD) and Circuit-Level (SPICE) simulation get more details with longer simulation time, models are existing.
- Gate (Verilog) and RTL (VHDL) focus on digital system modelling, limited analogue and mixed-signal modelling.
- A trade-off for accuracy and speed is Analogue Behavioural Modelling (ABM), Verilog-AMS or **VHDL-AMS**.

### ➤ VHDL-AMS

- A. Behavioural models are **simple, fast, continuous**, but no existing models
- B. Model developing: By **fitting** simulation results of cell behavioural to extract model parameters.
- C. To describe the cell behavioural by VHDL-AMS.

## ➤ Background — SRAM Cell

- ✓ One of the most important components in modern microprocessors and SOCs,
- ✓ Be considered as the benchmark circuit for developing of CMOS technology.
- ✓ Stability characterized by the static noise margin (**SNM**) during read period, which accounts for the ability of the cell to maintain stable data under parasitic noise and device mismatches.
- ✓ **SNM** is affected by **Random Doping**.



**Bias configuration For SNM**

# ➤ Effects of RDD on CMOS SRAM

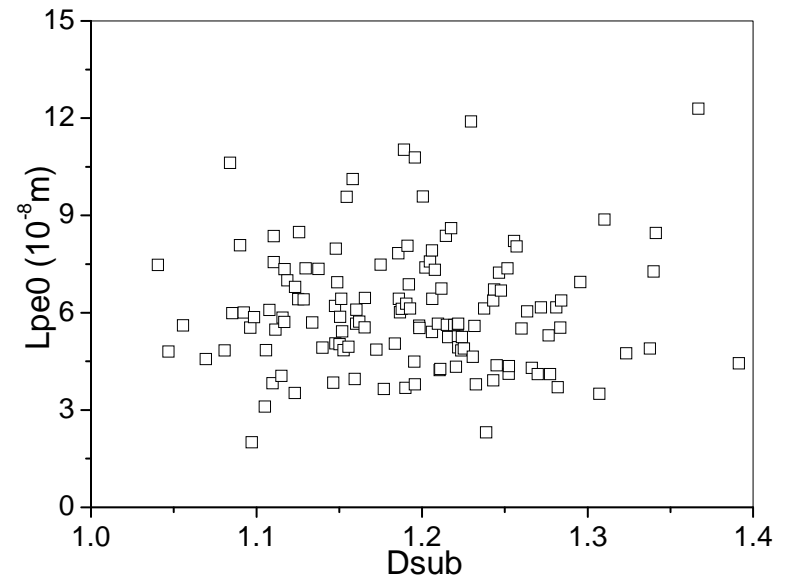
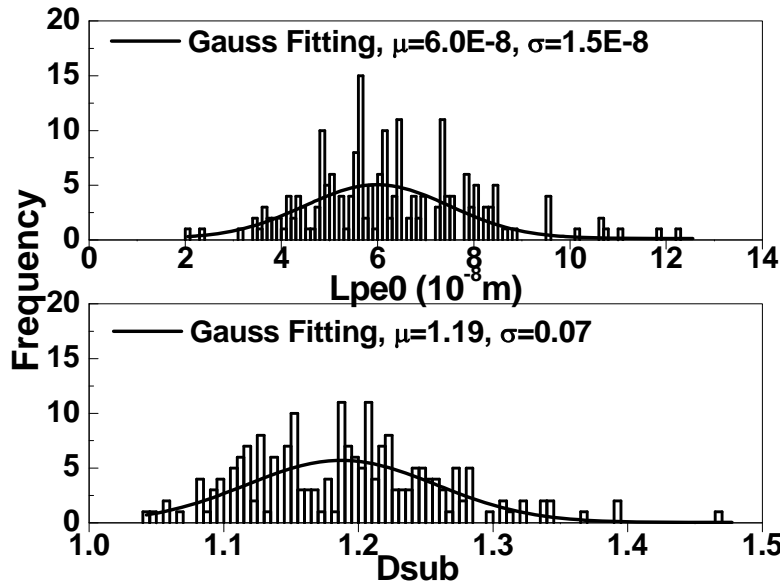
## RDD Related 35nm bulk Devices BSIM4 Model Parameters

**Lpe0**: Lateral non-uniform doping parameter at  $V_{bs}=0$ ,

**Dsub**: DIBL coefficient exponent in subthreshold region,

**Voff**, **a1**, **a2**, **Rdswmin** and **nfactor**.

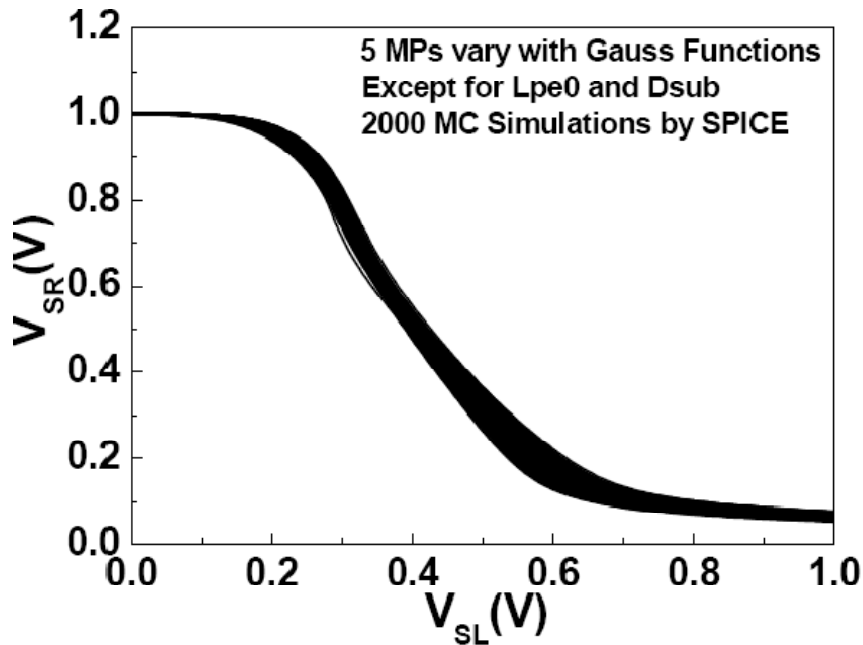
Main contributions to  $\Delta V_{th}$



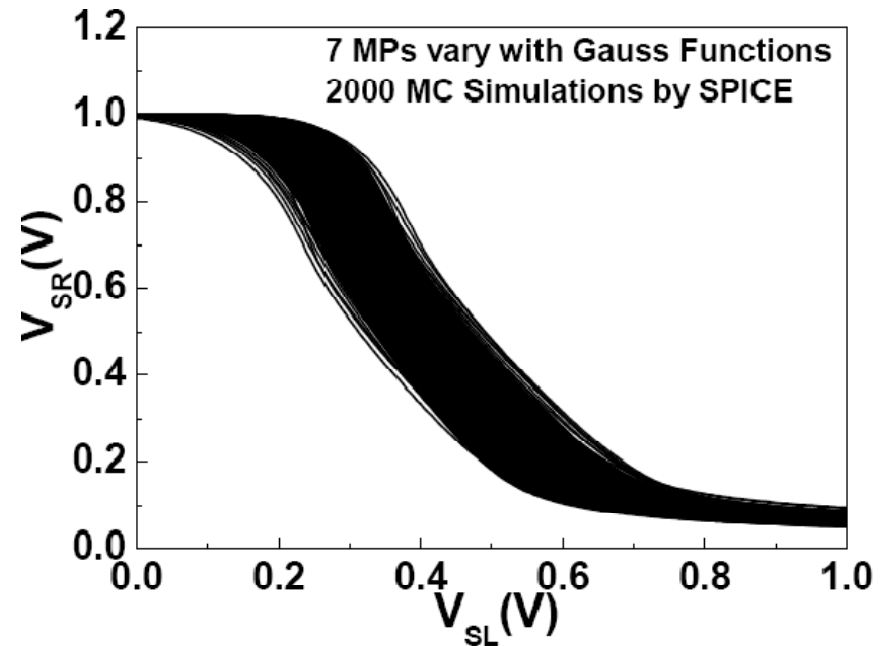
Parameters	Skewness	Kurtosis
Lpe0	0.6997	0.85
Dsub	0.6648	1.19



# ➤ Effects of RDD on CMOS SRAM (Cont.)



With Voff, a1, a2, Rdswmin  
and nfactor variations

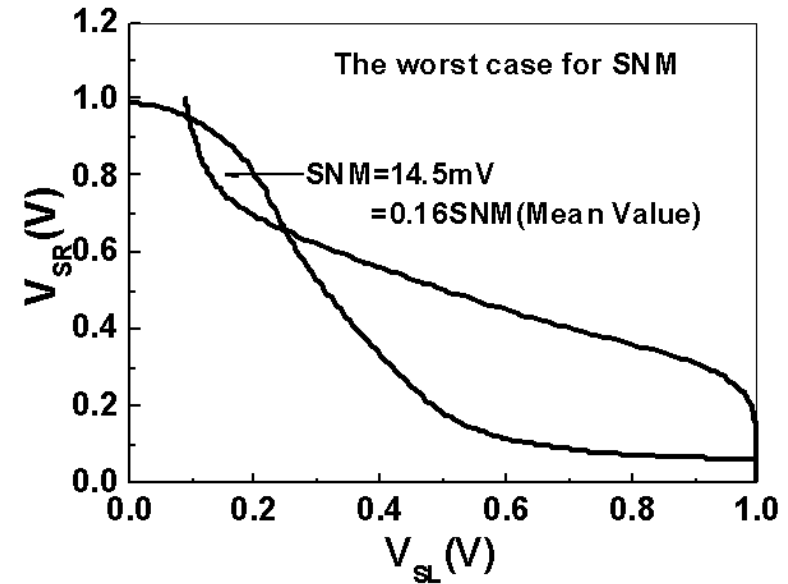
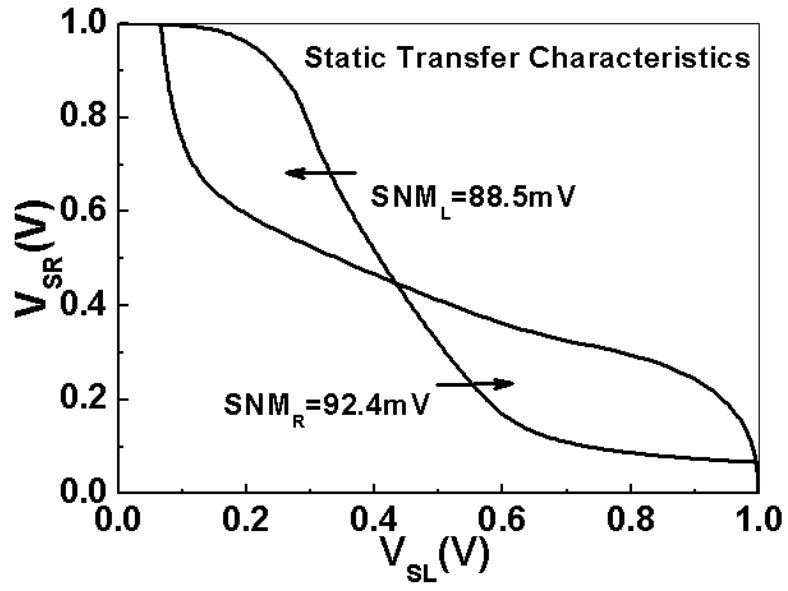


With all RDD  
parameters variations

## Simulation method

- Doing Monte Carlo simulations by H-SPICE,
- All the devices are set differently.

# ➤ Effects of RDD on CMOS SRAM (Cont.)



## SNM Definition

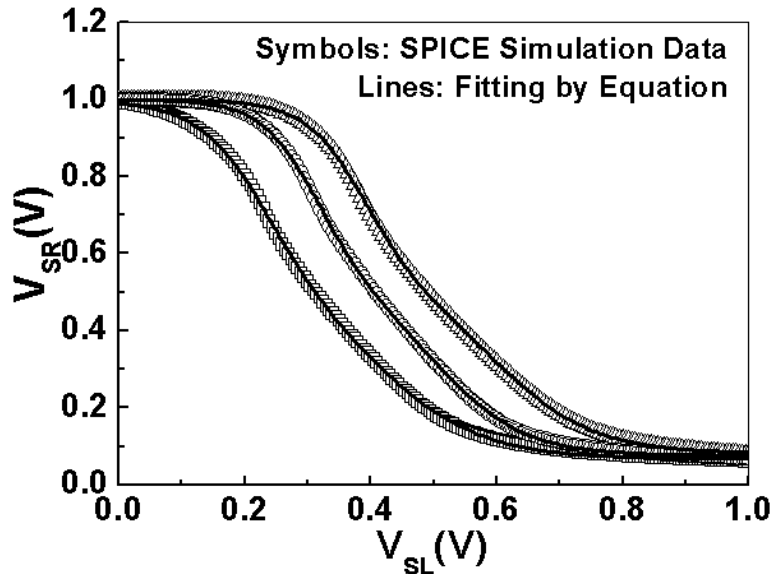
The smaller area formed by two Static Transfer Characteristics  
By sweeping  $V_{SL}$  or  $V_{SR}$ .

[The worst case for 2000 MC simulations](#)

# ➤ VHDL-AMS Behavioural Model Development

## SRAM STC Behavioural:

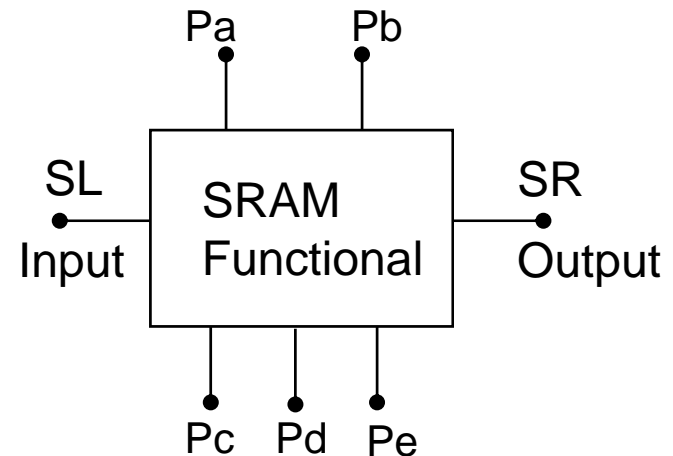
Two-level **Sigmoidal** function  
5 fitting parameters (FPs)



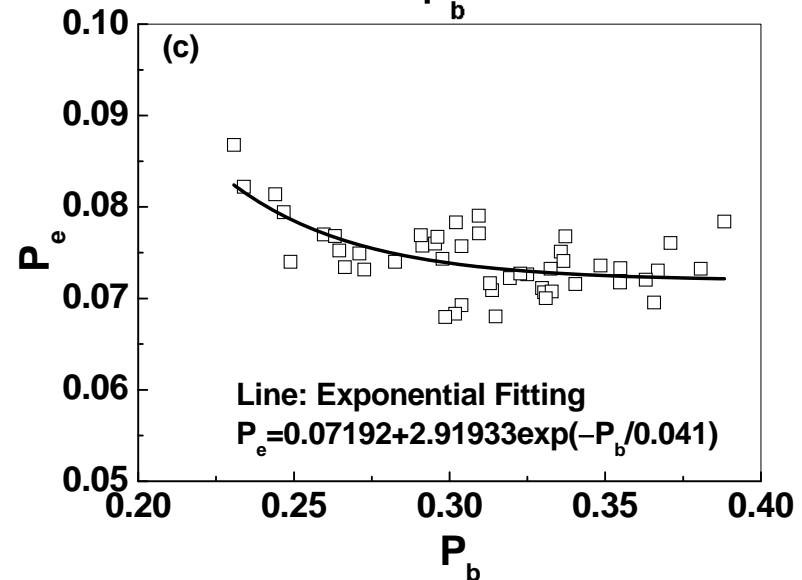
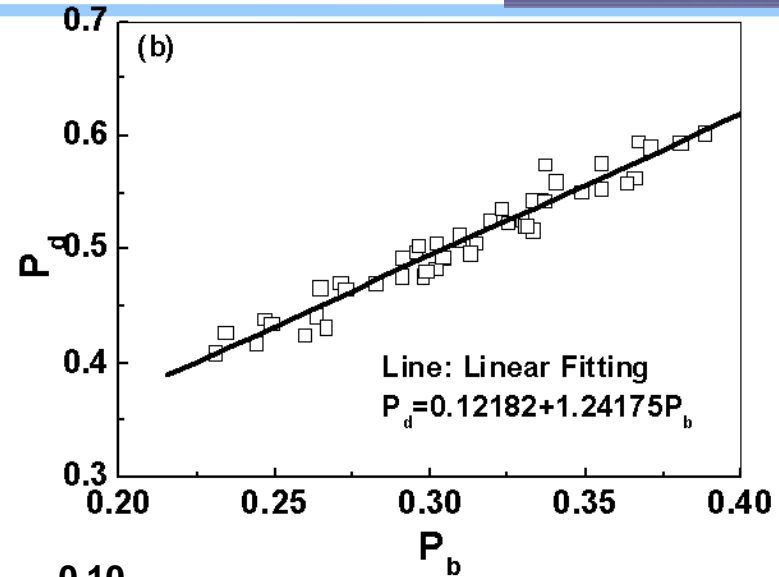
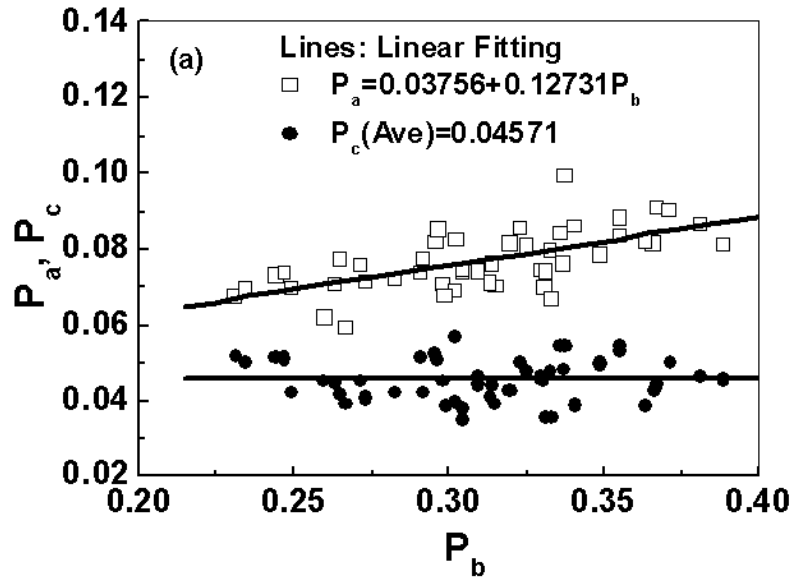
$$V_{SR} = P_a + \frac{1 - P_a}{2 \times \left[ 1 + e^{(V_{SL} - P_b) / P_c} \right]} + \frac{1 - P_a}{2 \times \left[ 1 + e^{(V_{SL} - P_d) / P_e} \right]}$$

## The SRAM Behavioural Model for RDD:

- Electrical input and output terminals,
- Five signal inputs for fitting parameters,
- Not all FPs are independent, only **Pb**.



➤ VHDL-AMS Behavioural Model Development (Cont.)

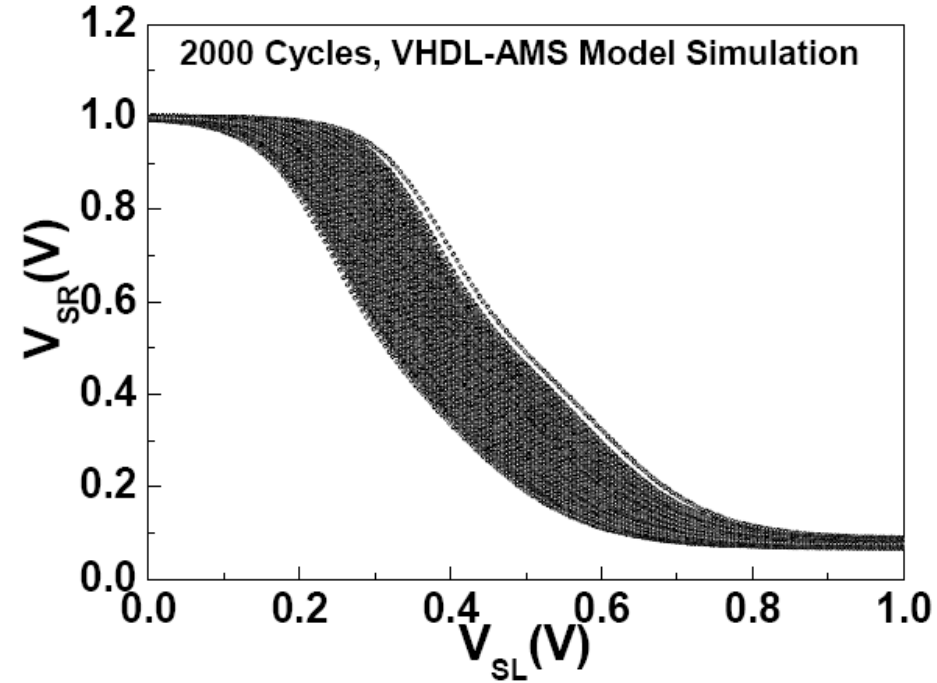
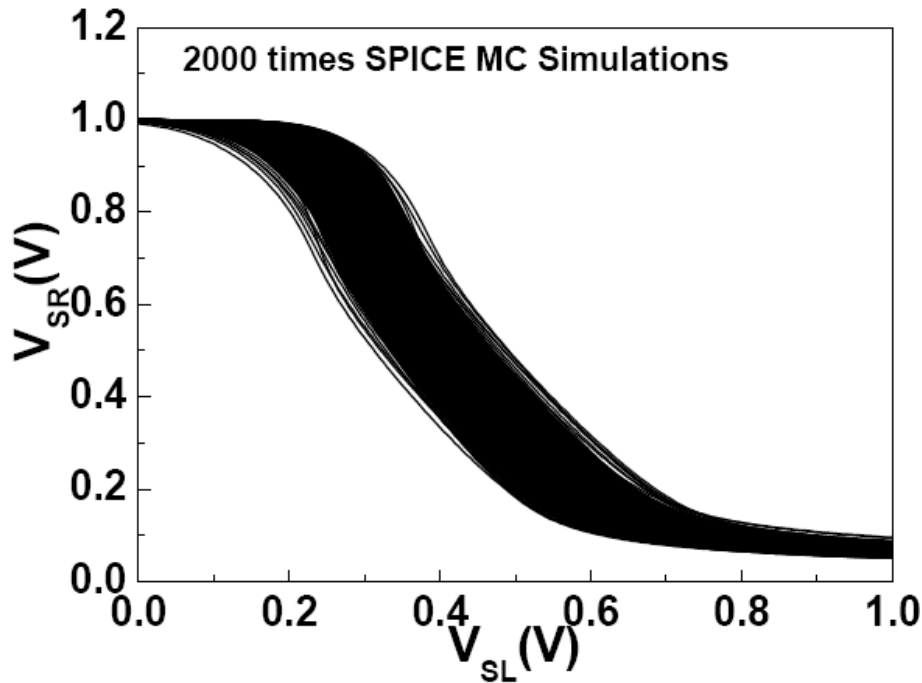


**Correlations between Fitting parameters,**

# VHDL-AMS Behavioural Model Development (Cont.)

Part I Main part	Part II Input Voltage
<pre> <b>entity SRAM is</b>   <b>port</b>(<b>terminal L,R:electrical</b>); end entity SRAM; architecture Behavioural of SRAM is   quantity Vin across L;   quantity Vout across Iout through R;   signal Vs1,Vs2:real:=0.0;   signal Pa,Pb,Pc,Pd,Pe:real:=0.0; begin p0:process is   variable s1 : positive; variable s2 : positive;   variable x1,x2 : real;          -- Uniform random variables begin UNIFORM(s1,s2,x1); UNIFORM(s1,s2,x2); <b>Vs1&lt;=sqrt(-2.0*log(x1))*cos(2.0*math_pi*x2);</b> <b>--Box-Muller Method</b> Vs2&lt;=0.305+Vs1*0.021; pa&lt;=0.03756+0.12731*Vs2; pb&lt;=Vs2; pc&lt;=0.04571; pd&lt;=0.12182+1.24175*Vs2; pe&lt;=0.07192+2.91933*exp(-Vs2/0.041); end process p0;  <b>Vout==Pa+(0.5-0.5*Pa)/(1.0+exp((Vin-Pb)/Pc))+(0.5-</b> <b>0.5*Pa)/(1.0+exp((Vin-Pd)/Pe));</b> break on Pa; break on Pb; break on Pc; break on Pd; break on Pe; end architecture Behavioural; </pre>	<pre> <b>entity Vinput is</b> generic(vhi,vlo:voltage;thi,tlo:real); <b>port</b>(<b>terminal L, R: electrical</b>); end entity Vinput; architecture behaviour of Vinput is   quantity V across I through L;   signal pulse:voltage:=0.0; begin <b>v==pulse'ramp(1.0E-9, 0.0);</b> pulse_proc: process begin pulse&lt;=vlo; wait for tlo; pulse&lt;=vhi; wait for thi; pulse&lt;=vlo; wait for 0 ms; end process; end architecture behaviour; </pre>
	<p style="text-align: center;"><b>Part III Testbench</b></p> <pre> <b>entity test_sram is</b> end entity test_sram; architecture test of test_sram is <b>terminal L,R: electrical;</b> <b>alias ground is ELECTRICAL_REF;</b> begin <b>Vin0: entity Vinput generic map (1.0, 0.0, 1.0E-9, 0.0) port map</b> <b>(L, ground);</b> <b>Sram0: entity SRAM port map (L,R);</b> end architecture; </pre>

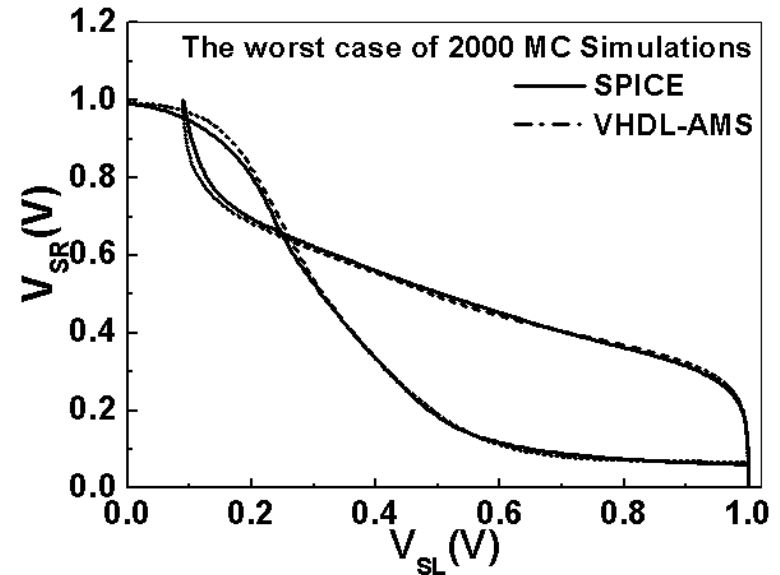
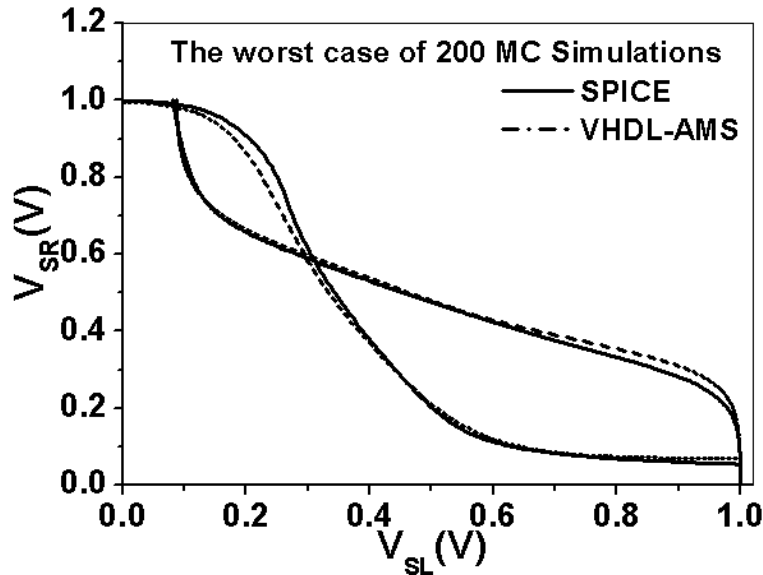
# ➤ Model Verification by SPICE



**STCs Comparison between SPICE and VHDL-AMS Model**

# ➤ Model Verification by SPICE (Cont.)

## Worst cases of STCs Comparison between SPICE and Behavioural Model



## Run times Comparison for SPICE and Behavioural Model

Simulation cycles	200	2000	20000
SPICE	7.3s	70.95s	893.93s
<b>VHDL-AMS</b>	2.0s	15.0s	145.0s
<b>Ratios</b>	<b>3.7</b>	<b>4.7</b>	<b>6.2</b>

## ➤ **Conclusions**

### ➤ **Device variability is increasing with Dimensions scaling down,**

Random discrete doping (**RDD**) is one of the main variability sources,

RDD results in  $V_{th}$ ,  $I_{ds}$  variations,

**Stability of 35 nm CMOS SRAM** digital cells such as **SNM** is impacted by RDD.

### ➤ **VHDL-AMS Behavioural model is developed for SRAM subject to RDD,**

STCs can be described by **two-level Sigmoidal** functions,

Parameters are extracted to develop behavioural model,

**Behavioural Model** is implemented by VHDL-AMS.

### ➤ **Model verification and Contribution of this work**

The **accuracy** and **efficiency** are confirmed by comparing with SPICE simulation,

One can get useful information of SRAM stability resulting from RDD by proposed Model without doing transistor-level simulation.



***THANKS  
FOR YOUR ATTENTION !***

***Questions/Answers ?***